



Press Release

More Discrete Power: Infineon Launches New TO-247PLUS Package Enabling Current Rates of up to 120A

Munich – November 24, 2014 – Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) expands its discrete IGBT portfolio for high power applications introducing the TO-247PLUS package. The new package enables up to 120A IGBT co-packed with a full rated diode in the same footprint and pin-out as JEDEC standard TO-247-3. The TO-247PLUS can be used in industrial applications such as UPS, welding, solar, industrial drives as well as automotive applications such as powertrain inverter to upgrade existing designs for higher power output or to improve the thermal conditions in the application consequently improving the system reliability and lifetime. The higher current capability of the TO-247PLUS allows for reducing the number of devices in parallel thus enabling more compact product designs.

The new package is designed for clip or pressure mounting to the heat sink. These mounting techniques ensure homogeneous distribution of pressure over the package, better heat conductivity and higher mechanical stability even under strong vibrations and mechanical shocks.

Due to the absence of the mounting hole the TO-247PLUS package may accommodate a 70% larger silicon die area compared to standard TO-247. Additionally, the 26% larger thermal pad area contributes up to a 20% lower thermal resistance $R_{th(jh)}$ compared to standard TO-247. The TO-247PLUS package body has special “plastic trousers” to increase the creepage distance to 4.25mm – 2mm larger than the TO-247-3. The special plastic body compound of the TO-247PLUS package has tighter tolerances to clip pressure while a new bond wiring concept allows a DC collector current increase from 80A to 160A contributing to a better reliability and longer lifetime of the IGBT.

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Availability and further information

Samples of the new TO-247PLUS discrete TRENCHSTOP IGBT in 100A and 120A are available today, with volume production scheduled for the first quarter of 2015. Further information on the new TO-247PLUS IGBT is available at www.infineon/TO-247PLUS.

About Infineon

[Infineon](http://www.infineon.com) Technologies AG, Neubiberg, Germany, offers semiconductor and system solutions addressing three central challenges to modern society: [energy efficiency](#), [mobility](#), and [security](#). In the 2013 fiscal year (ending September 30), the company reported sales of Euro 3.84 billion with close to 26,700 employees worldwide. Infineon is listed on the Frankfurt Stock Exchange (ticker symbol: IFX) and in the USA on the over-the-counter market OTCQX International Premier (ticker symbol: IFNNY).

Further information is available at www.infineon.com

This news release is available online at www.infineon.com/press

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